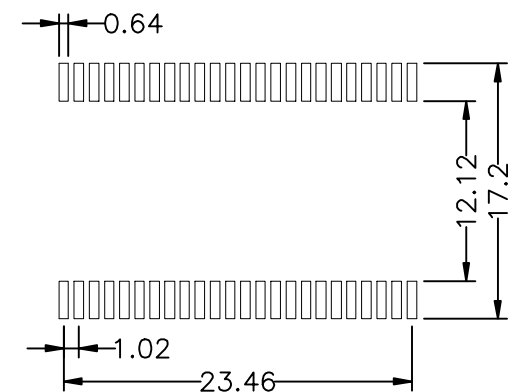
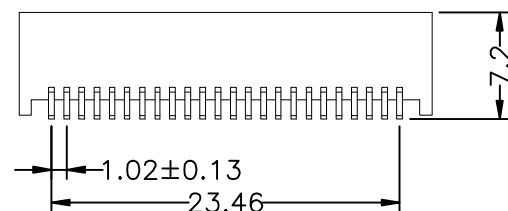
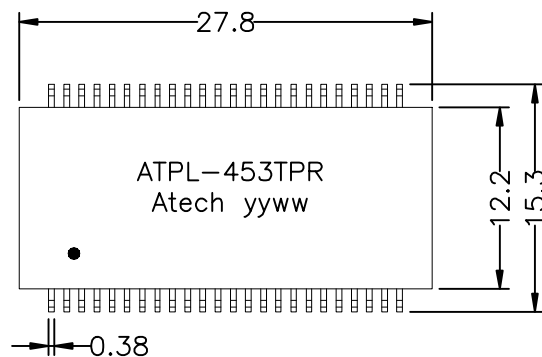
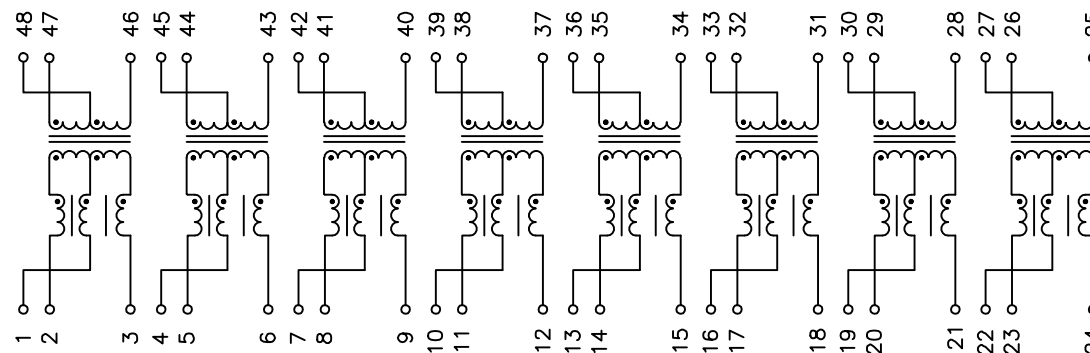
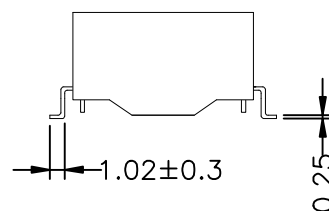




SUGGESTED PCB LAYOUT



ELECTRICAL CHARACTERISTICS @25°C :

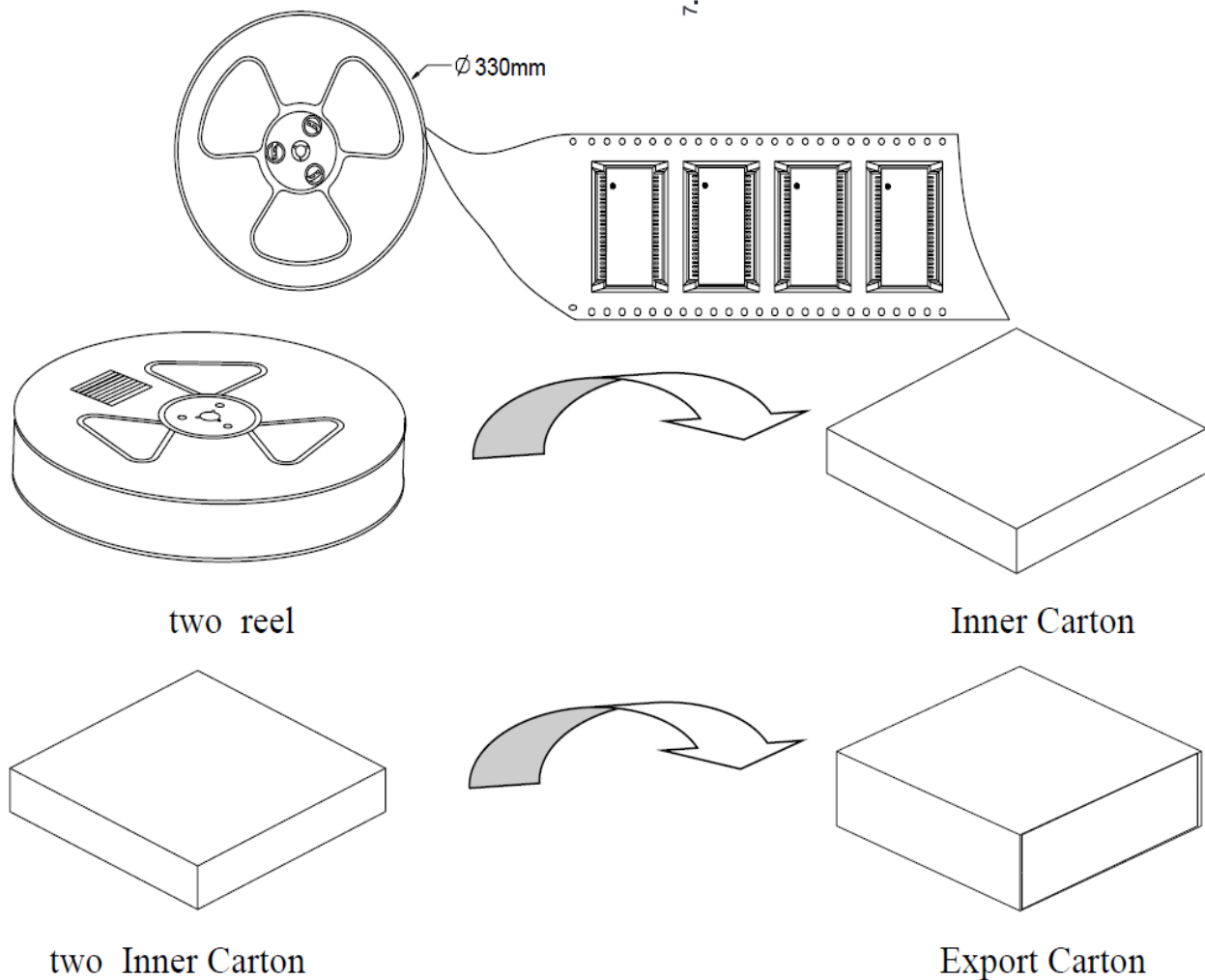
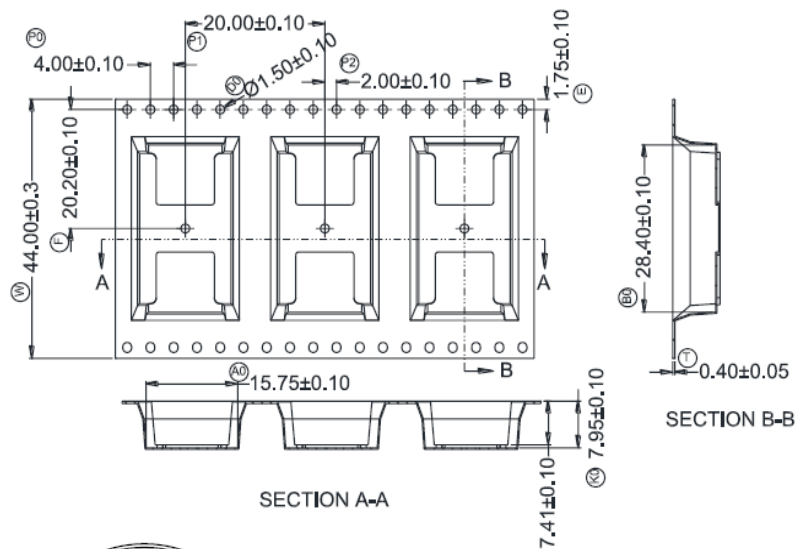
1. INSULATION HI-POT(PRI./SEC.) : 1500Vrms, 1mA, 60SEC
2. TURN RATIO ($\pm 5\%$) : TX = 1CT : 1CT , RX = 1CT : 1CT
3. OCL : 350uH MIN. @100kHz, 0.1V WITH 8mA DC BIAS
4. LEAKAGE INDUCTANCE : 0.5uH MAX @100kHz, 0.2V
5. DCR : 1.2 Ω MAX.
6. C_{ww} : 35pF MAX @100kHz, 0.2V
7. INSERTION LOSS : -1.1dB MAX. (@1-100MHz)
8. RETURN LOSS (dB MIN.) :

1-30MHz	40MHz	50MHz	60-80MHz	100MHz
-18	-14.4	-13.1	-10	-8
9. CROSS TALK : 1-100MHz : -30dB MIN.
10. CMRR : 1-100MHz : -30dB MIN.
11. OPERATING TEMPERATURE RANGE : -40°C~+85°C
12. IEEE802.3at COMPLIANT PERFORMANCE
---720mA Current capability
13. RoHS COMPLIANT

								TITLE 10/100/1000 BASE-PoE+ TRANSFORMER	
								DWG. NO. ATPL-453TPR	
	RELEASE	09/26/2018	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 09/26/18	P/N:		DRAW SHIRLEY
REVISIONS									

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE XX.XX±0.25 0.XX±0.05

3. Package:



Package Quantity:

One Reel=350Pcs

One Inner Carton=350*2=700Pcs

One Export Carton=700*2=1400Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmmax)	150°C	200°C
Time (Tsmmin to Tsmmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max